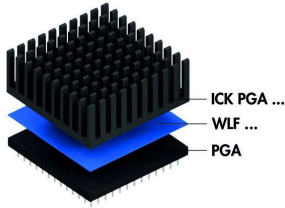


Data sheet Product ICK PGA 16 x 16 x 8



Heatsinks and active heatsinks for processors>Heatsinks for PGA
 40 x 40 x 8 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	40 mm
height:	8 mm
plate thickness:	3.5 mm
length:	40 mm
thermal resistance:	14 - 3.2 K/W
dissipation loss:	4.9 W
surface:	black anodised

Technical Drawing

